Celanese
The chemistry inside innovation™

HOSTAFORM® C 13021 XAP®

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POM copolymer
Easy flowing Injection molding type for precision molded parts and thin-walled molded parts with high rigidity, hardness and toughness; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation.
Emission according to VDA 275 < 10 mg/kg
Monomers and additives are listed in EU-Regulation (EU) 10/2011 FDA compliant according to 21 CFR 177.2470
Burning rate ISO 3795 and FMVSS 302 < 75 mm/min for a thickness more than 1 mm.
Ranges of applications: automotive engineering, precision engineering, electric and electronical industry, domestic appliances.
FDA = Food and Drug Administration (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Resin Identification	POM	ISO 1043
Part Marking Code	>POM<	ISO 11469

Rheological properties

Melt volume-flow rate	12	cm^3/10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	2.0	%	ISO 294-4, 2577
Moulding shrinkage, normal	1.8	%	ISO 294-4, 2577

Typical mechanical properties

Tensile modulus	2900	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	65	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	9	%	ISO 527-1/-2
Nominal strain at break	25	%	ISO 527-1/-2
Flexural modulus	2800	MPa	ISO 178
Tensile creep modulus, 1h	2500	MPa	ISO 899-1
Tensile creep modulus, 1000h	1300	MPa	ISO 899-1
Charpy impact strength, 23°C	200	kJ/m^2	ISO 179/1eU
Charpy impact strength, -30°C	200	kJ/m^2	ISO 179/1eU
Charpy notched impact strength, 23°C	6.5	kJ/m^2	ISO 179/1eA
Charpy notched impact strength, -30°C	6	kJ/m^2	ISO 179/1eA
Ball indentation hardness, H 358/30	143	MPa	ISO 2039-1
Poisson's ratio	0.37[C]		

[C]: Calculated

Thermal properties

Melting temperature, 10°C/min	166	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	106	°C	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	110	E-6/K	ISO 11359-1/-2
Thermal conductivity of melt	0.155	W/(m K)	ISO 22007-2
Specific heat capacity of melt	2210	J/(kg K)	ISO 22007-4

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Flammability

Burning Behav. at 1.5mm nom. thickn.	HB	class	IEC 60695-11-10
Thickness tested	1.5	mm	IEC 60695-11-10
Burning Behav. at thickness h	HB	class	IEC 60695-11-10
Thickness tested	3	mm	IEC 60695-11-10
UL recognition	yes		UL 94
FMVSS Class	B		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	41.3	mm/min	ISO 3795 (FMVSS 302)

Electrical properties

Relative permittivity, 100Hz	4		IEC 62631-2-1
Relative permittivity, 1MHz	4		IEC 62631-2-1
Dissipation factor, 100Hz	20	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	50	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Electric strength	35	kV/mm	IEC 60243-1
Comparative tracking index	600		IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	0.65	%	Sim. to ISO 62
Density	1410	kg/m³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	200	°C
Min. melt temperature	190	°C
Max. melt temperature	210	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	100	°C
Min. mould temperature	80	°C
Max. mould temperature	120	°C
Hold pressure range	60 - 120	MPa
Back pressure	4	MPa
Ejection temperature	140	°C

Characteristics

Processing	Injection Moulding
Delivery form	Pellets
Additives	Release agent
Special characteristics	Low emissions

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Additional information

Injection molding

Preprocessing

To achive low emission values pre drying using a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,1 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

It is normally not necessary to dry HOSTAFORM. However, should there be surface moisture (condensate) on the molding compound as a result of incorrect storage, drying is required. A circulating air drying cabinet can be used for this purpose if the granul

Storage

The product can then be stored in standard conditions until processed.

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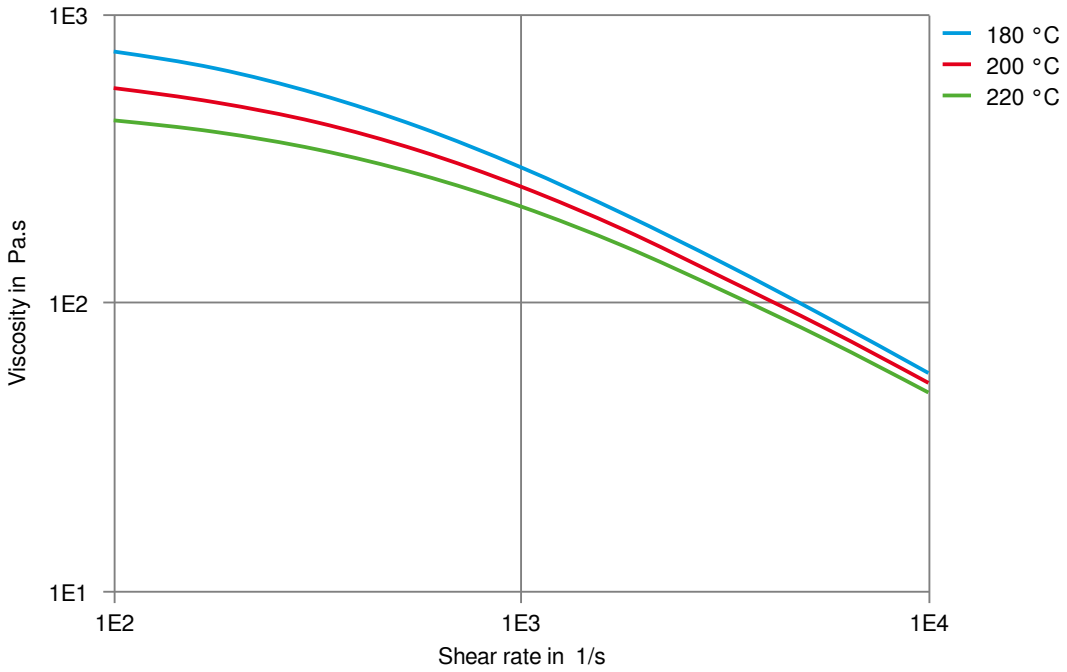
Viscosity-shear rate



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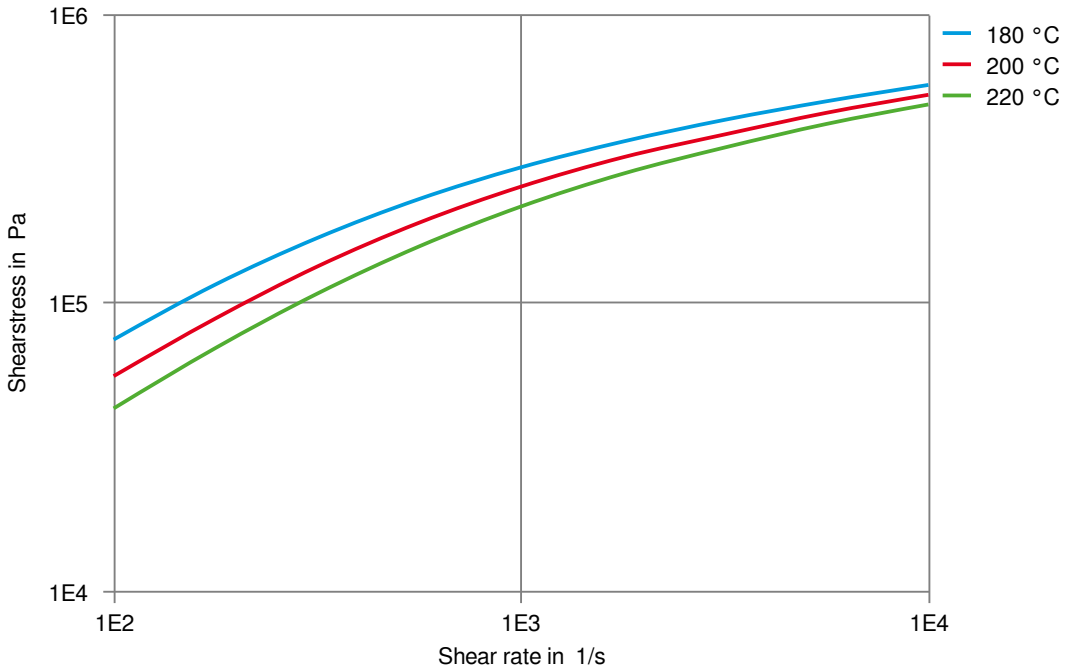
Shearstress-shear rate



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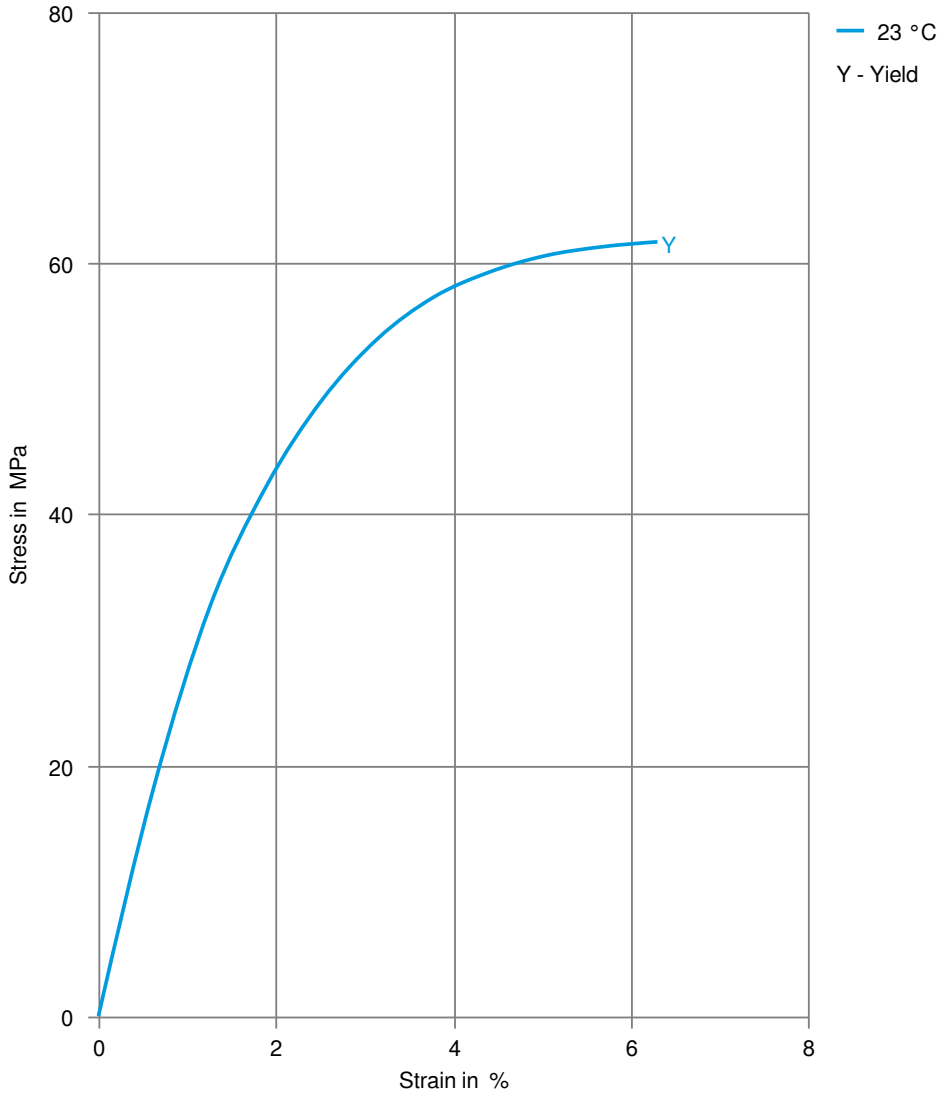
Stress-strain



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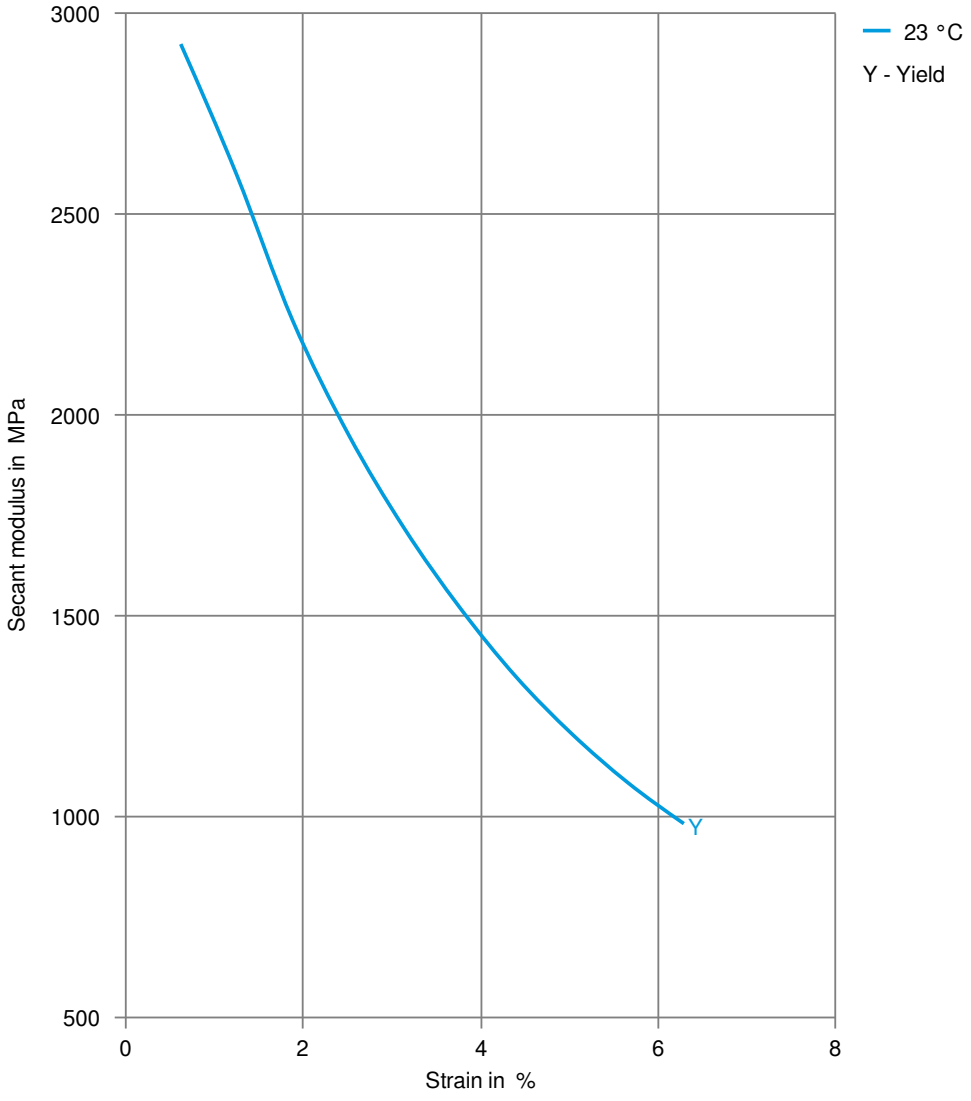
Secant modulus-strain



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